

HT-03-026



IFW

May 21, 2004

To: Commissioner for Patents  
P.O.Box 1450  
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572  
28 Davis Avenue  
Poughkeepsie, N.Y. 12603

Subject: | Serial No. 10/823,098 04/13/04 |  
Kowang Liu et al.  
HEAT EXTRACTOR FOR MAGNETIC  
READER-WRITER  
| \_\_\_\_\_ |

#### INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation  
In An Application.

The following Patents and/or Publications are submitted to  
comply with the duty of disclosure under CFR 1.97-1.99 and  
37 CFR 1.56.

#### CERTIFICATE OF MAILING

I hereby certify that this correspondence is being  
deposited with the United States Postal Service as first class  
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P.O. Box 1450, Alexandria, VA 22313-1450, on May 24, 2004.

Stephen B. Ackerman, Reg.# 37761

Signature/Date

SB Ackerman 5/24/04

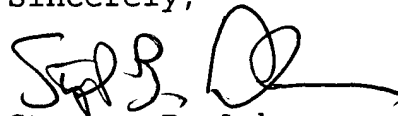
HT-03-026

U.S. Patent 6,181,514 to Santini et al., "Scaled Write Head with High Recording Density and High Data Rate," discloses a non-organic insulating material on the coil as a heat dissipater.

U.S. Patent 6,466,404 to Crue, Jr. et al. "Magnetic Read/Write Device with Insulated Coil Layer Recessed into Pole," discloses AIN or other material as an undercoat under the coil to dissipate heat.

U.S. Patent 6,381,094 to Gill, "Shield Structure with a Heat Sink Layer for Dissipating Heat from a Read Sensor," teaches using gold and tantalum as a heat sink layer.

Sincerely,

A handwritten signature in black ink, appearing to read 'SBA', followed by a large, stylized circular flourish.

Stephen B. Ackerman,  
Reg. No. 37761

(Use several sheets if necessary)

Application Number

10/823,098

Ko Wang Lin et al.

04/13/04

Group Art Unit

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DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.